

P-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | |
|---------------------|-------------------------------------|--------------------|-----------------------|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (A) | Q _g (Typ.) |
| - 30 | 0.0032 at V _{GS} = - 10 V | - 100 | 78 nC |
| | 0.0050 at V _{GS} = - 4.5 V | - 80 | |

FEATURES

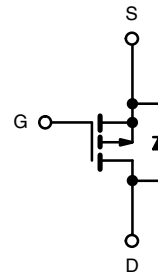
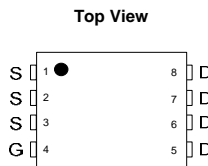
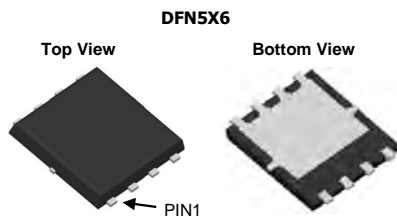
- Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested



RoHS
COMPLIANT

APPLICATIONS

- Notebook
- Load Switch



P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted | | | |
|---|-----------------------------------|------------------------|------------------------|
| Parameter | Symbol | Limit | Unit |
| Drain-Source Voltage | V _{DS} | - 30 | V |
| Gate-Source Voltage | V _{GS} | ± 20 | |
| Continuous Drain Current (T _J = 150 °C) | I _D | T _C = 25 °C | - 100 |
| | | T _C = 70 °C | - 75 |
| | | T _A = 25 °C | - 31.6 ^{b, c} |
| | | T _A = 70 °C | - 25.3 ^{b, c} |
| Pulsed Drain Current | I _{DM} | - 300 | A |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | |
| | | T _A = 25 °C | - 5.6 ^{b, c} |
| Single Pulse Avalanche Current | I _{AS} | - 40 | mJ |
| Single Pulse Avalanche Energy | E _{AS} | 80 | |
| Maximum Power Dissipation | P _D | T _C = 25 °C | 104 |
| | | T _C = 70 °C | 66.6 |
| | | T _A = 25 °C | 6.25 ^{b, c} |
| | | T _A = 70 °C | 4.0 ^{b, c} |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | - 55 to 150 | °C |
| Soldering Recommendations (Peak Temperature) ^{d, e} | | 260 | |

| THERMAL RESISTANCE RATINGS | | | | | |
|---|--------------|-------------------|---------|---------|------|
| Parameter | | Symbol | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient ^{b, f} | t ≤ 10 s | R _{thJA} | 15 | 20 | °C/W |
| Maximum Junction-to-Case (Drain) | Steady State | R _{thJC} | 0.9 | 1.2 | |

Notes:

- Package limited.
- Surface Mounted on 1" x 1" FR4 board.
- t = 10 s.
- The DFN5x6 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Maximum under Steady State conditions is 54 °C/W.

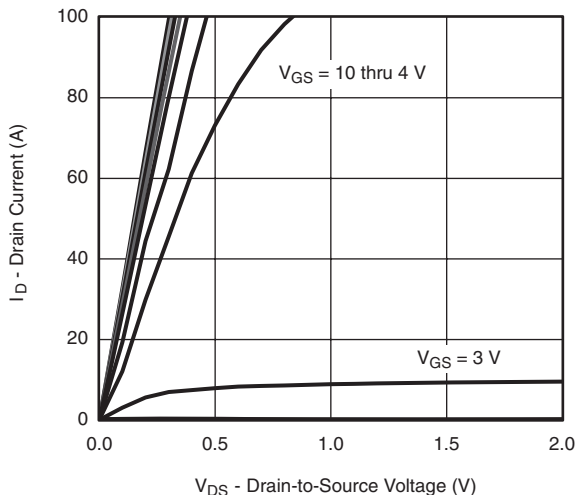
| SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted | | | | | | |
|---|-------------------------|--|------|--------|-----------|---------------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$ | -30 | | | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | $I_D = -250\text{ }\mu\text{A}$ | | -31 | | mV/°C |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | 6.5 | | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$ | -1.0 | | -3.0 | V |
| Gate-Source Leakage | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -30\text{ V}, V_{GS} = 0\text{ V}$ | | | -1 | μA |
| | | $V_{DS} = -30\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$ | | | -10 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} = -5\text{ V}, V_{GS} = -10\text{ V}$ | -30 | | | A |
| Drain-Source On-State Resistance ^a | $R_{DS(on)}$ | $V_{GS} = -10\text{ V}, I_D = -20\text{ A}$ | | 0.0032 | | Ω |
| | | $V_{GS} = -4.5\text{ V}, I_D = -15\text{ A}$ | | 0.005 | | |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = -15\text{ V}, I_D = -20\text{ A}$ | | 95 | | S |
| Dynamic^b | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = -15\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ | | 8650 | | pF |
| Output Capacitance | C_{oss} | | 1215 | | | |
| Reverse Transfer Capacitance | C_{rss} | | 1125 | | | |
| Total Gate Charge | Q_g | $V_{DS} = -15\text{ V}, V_{GS} = -10\text{ V}, I_D = -20\text{ A}$ | | 167 | 250 | nC |
| | | | | 78 | 120 | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = -15\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -20\text{ A}$ | | 27 | | |
| Gate-Drain Charge | Q_{gd} | | | 35 | | |
| Gate Resistance | R_g | $f = 1\text{ MHz}$ | | 1.7 | | Ω |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -15\text{ V}, R_L = 15\text{ }\Omega$ $I_D \cong -1.0\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$ | | 25 | 40 | ns |
| Rise Time | t_r | | | 15 | 30 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 110 | 170 | |
| Fall Time | t_f | | | 30 | 50 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -15\text{ V}, R_L = 15\text{ }\Omega$ $I_D \cong -1.0\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 1\text{ }\Omega$ | | 110 | 170 | |
| Rise Time | t_r | | | 100 | 150 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 100 | 150 | |
| Fall Time | t_f | | | 50 | 75 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source-Drain Diode Current | I_S | $T_C = 25\text{ }^\circ\text{C}$ | | | 60 | A |
| Pulse Diode Forward Current ^a | I_{SM} | | | | 100 | |
| Body Diode Voltage | V_{SD} | $I_S = -5\text{ A}$ | | -0.74 | -1.1 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $I_F = 3.5\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$ | | 50 | 100 | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | | | 65 | 130 | nC |
| Reverse Recovery Fall Time | t_a | | | 26 | | ns |
| Reverse Recovery Rise Time | t_b | | | 24 | | |

Notes:

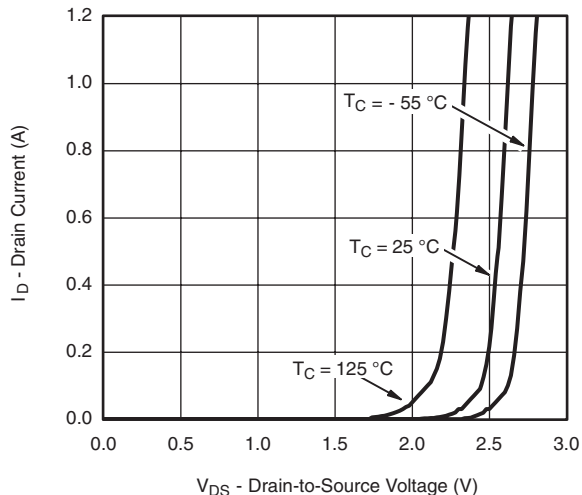
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

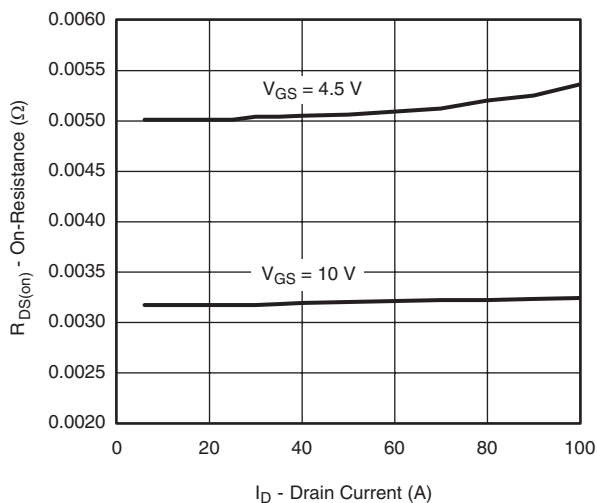
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



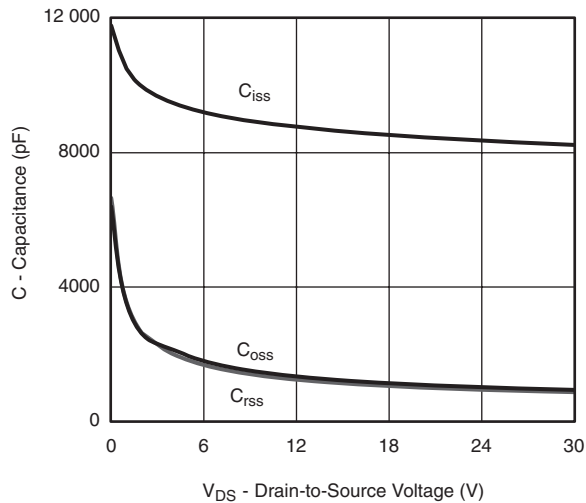
Output Characteristics



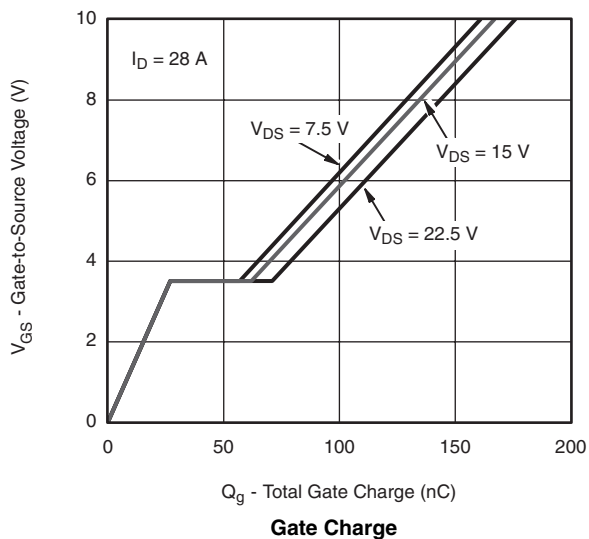
Transfer Characteristics



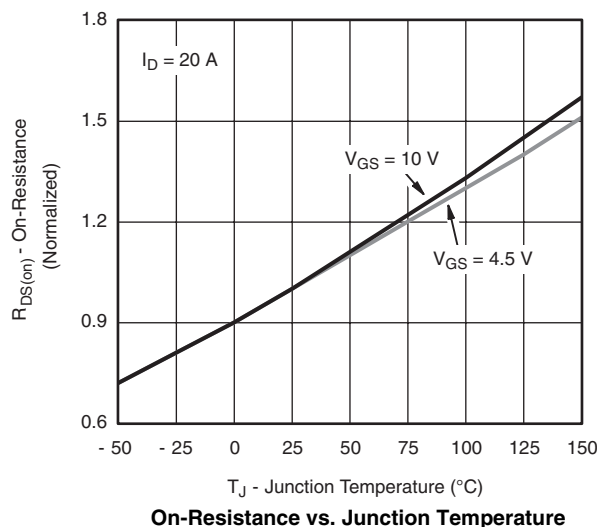
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

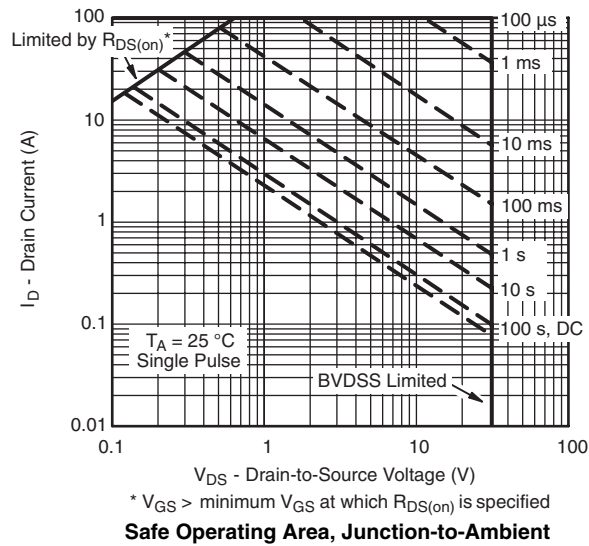
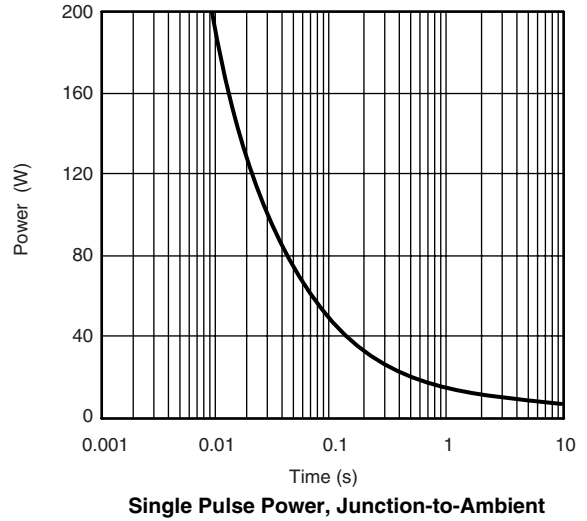
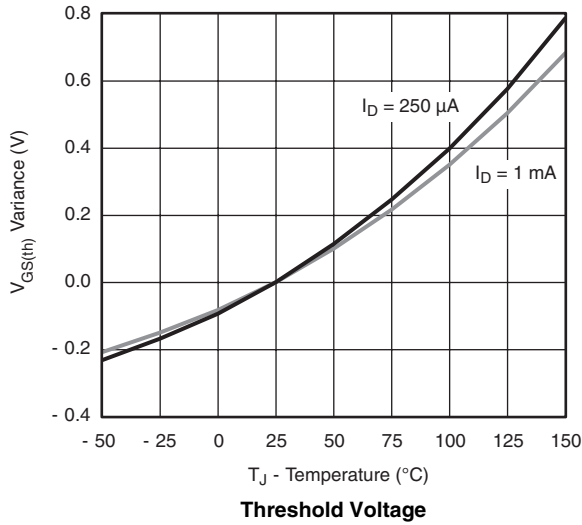
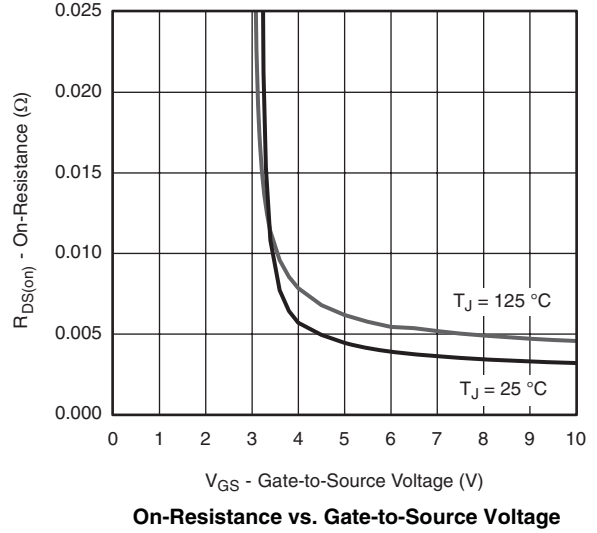
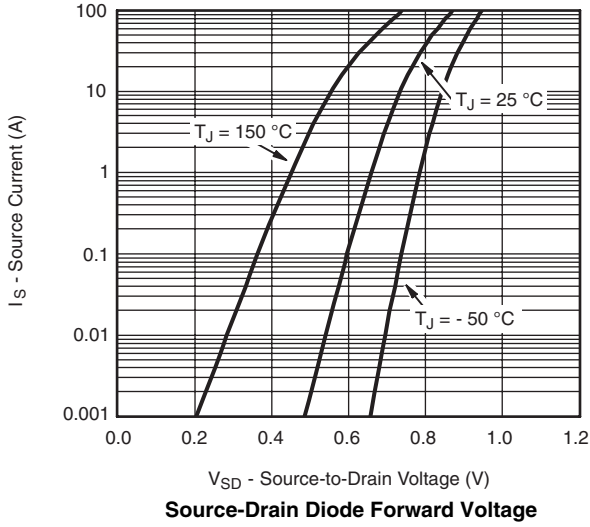


Gate Charge

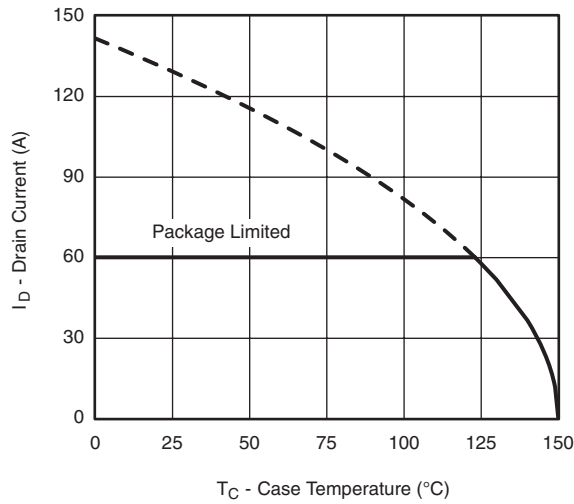


On-Resistance vs. Junction Temperature

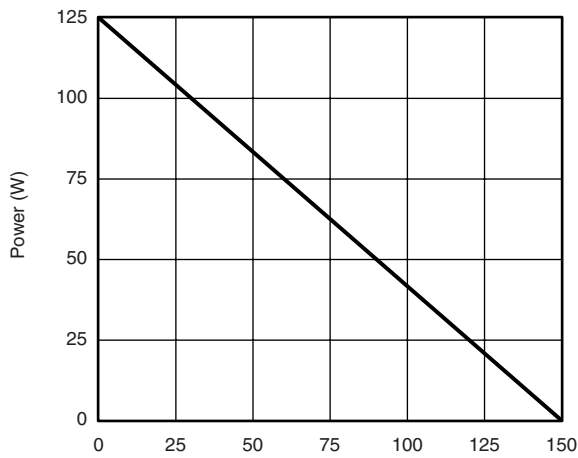
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



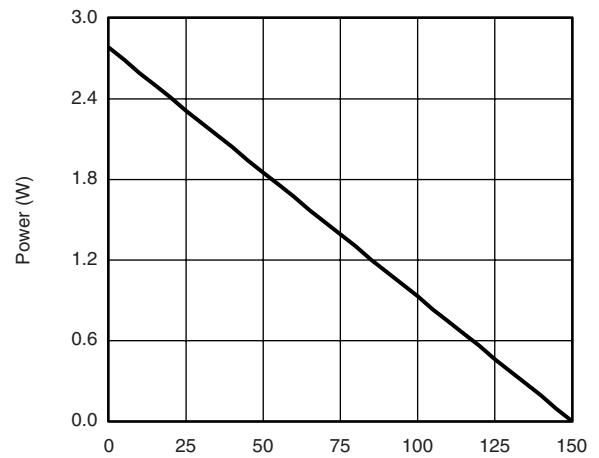
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



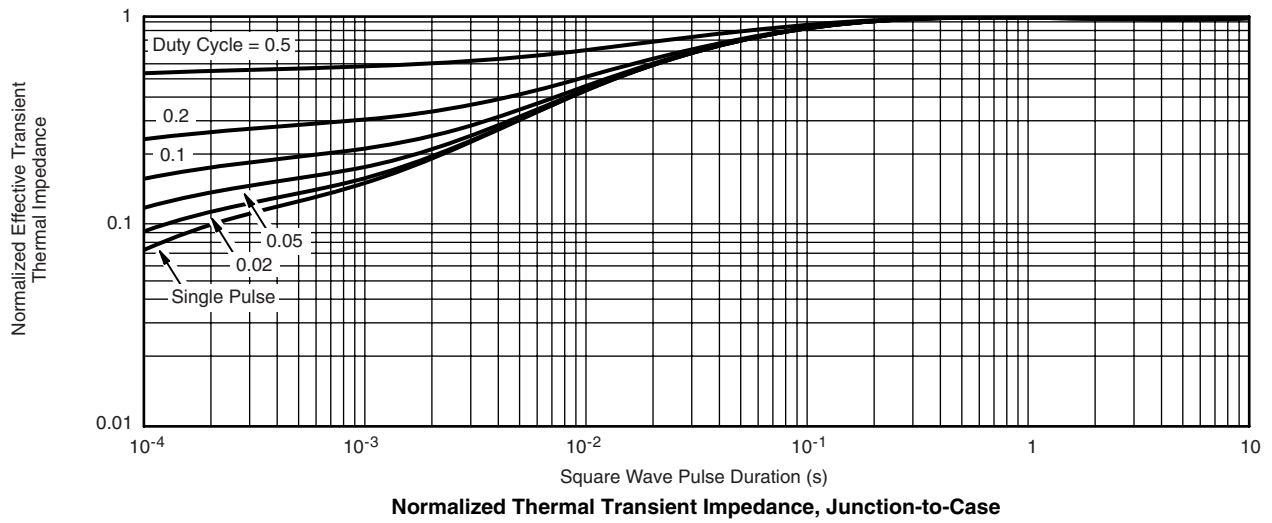
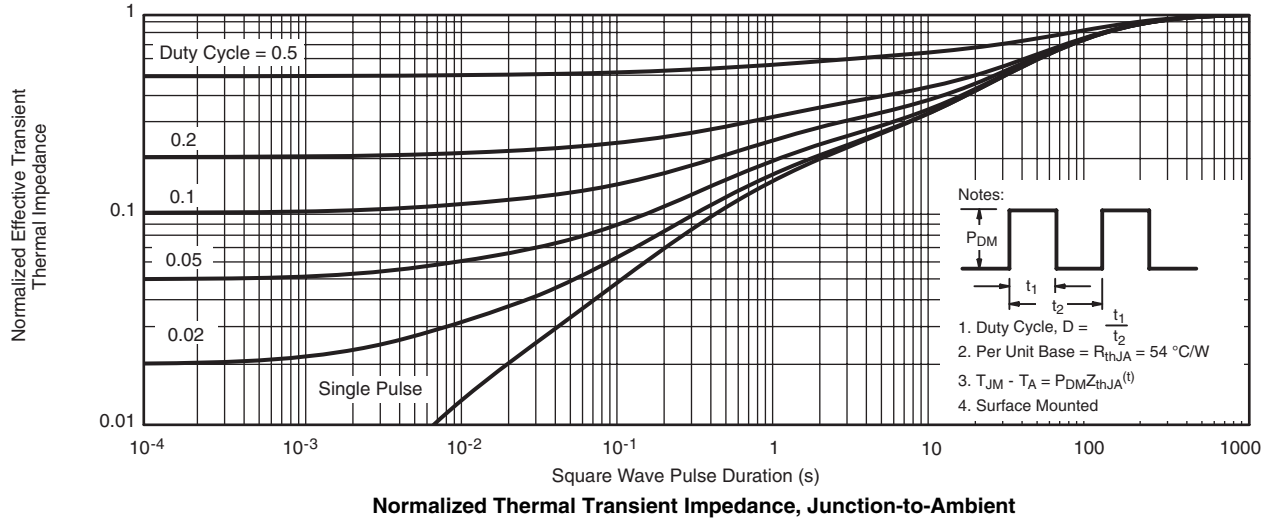
Power, Junction-to-Case



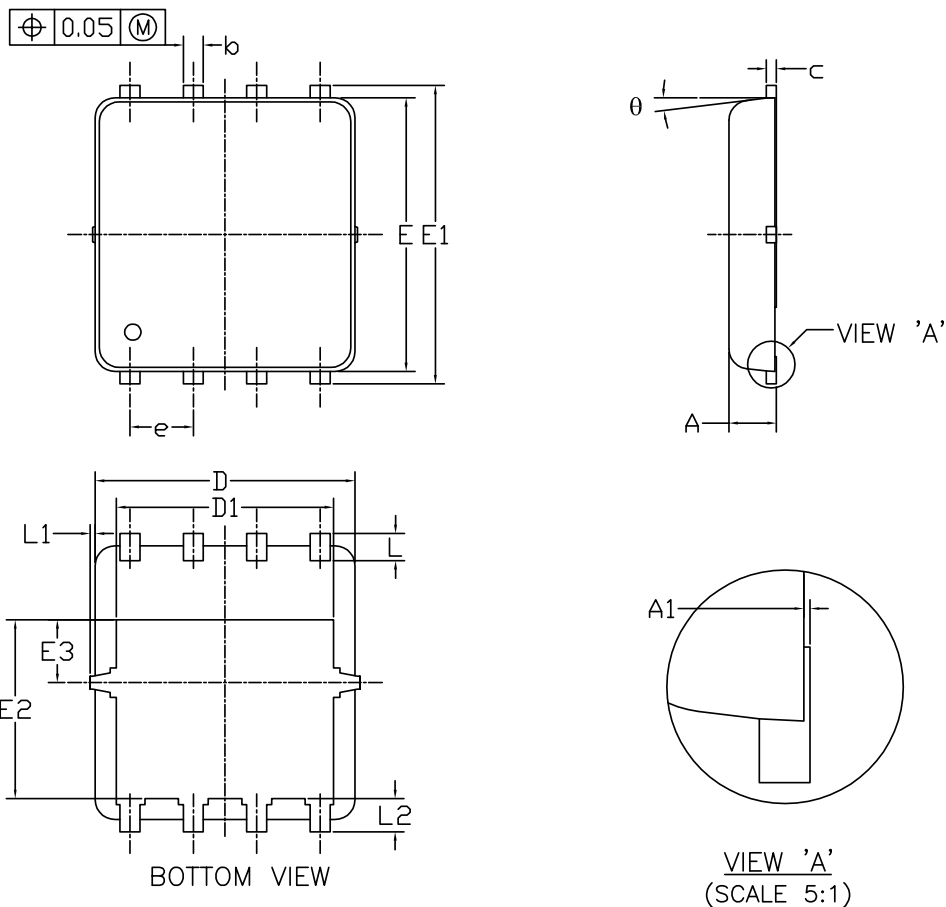
Power, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

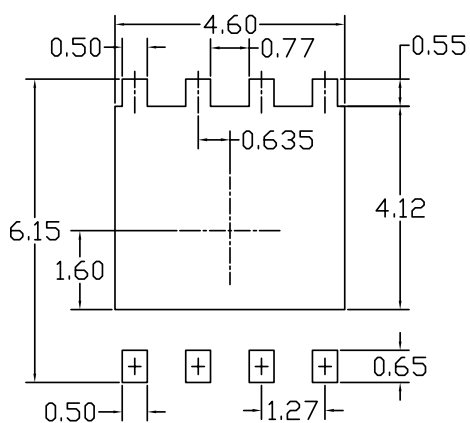
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



DFN5x6_8L_EP1_P PACKAGE OUTLIN



RECOMMENDED LAND PATTERN

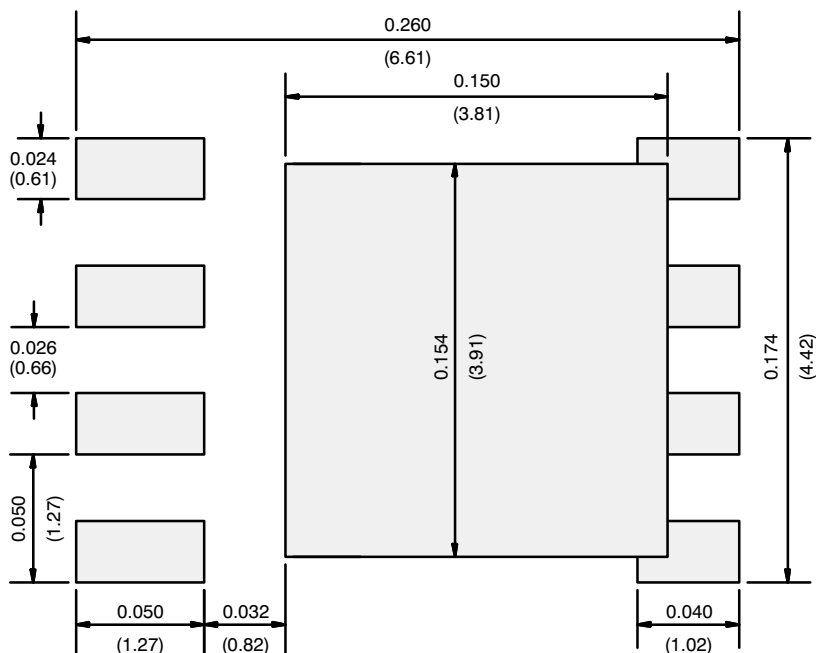


| SYMBOLS | DIMENSIONS IN MILLIMETERS | | | DIMENSIONS IN INCHES | | |
|---------|---------------------------|-------|-------|----------------------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.85 | 0.95 | 1.00 | 0.033 | 0.037 | 0.039 |
| A1 | 0.00 | --- | 0.05 | 0.000 | --- | 0.002 |
| b | 0.30 | 0.40 | 0.50 | 0.012 | 0.016 | 0.020 |
| c | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| D | 5.10 | 5.20 | 5.30 | 0.201 | 0.205 | 0.209 |
| D1 | 4.25 | 4.35 | 4.45 | 0.167 | 0.171 | 0.175 |
| E | 5.45 | 5.55 | 5.65 | 0.215 | 0.219 | 0.222 |
| E1 | 5.95 | 6.05 | 6.15 | 0.234 | 0.238 | 0.242 |
| E2 | 3.525 | 3.625 | 3.725 | 0.139 | 0.143 | 0.147 |
| E3 | 1.175 | 1.275 | 1.375 | 0.046 | 0.050 | 0.054 |
| e | 1.27 BSC | | | 0.050 BSC | | |
| L | 0.45 | 0.55 | 0.65 | 0.018 | 0.022 | 0.026 |
| L1 | 0 | --- | 0.15 | 0 | --- | 0.006 |
| L2 | 0.68 REF | | | 0.027 REF | | |
| θ | 0° | --- | 10° | 0° | --- | 10° |

NOTE

- PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
- CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

RECOMMENDED MINIMUM PADS FOR DFN5 x 6



Recommended Minimum Pads
Dimensions in Inches/(mm)

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